

FEATURES

- For surface mounted applications
- High temperature metallurgically bonded-no compression contacts as found in other diode-constructed rectifiers
- Glass passivated junction
- Built-in strain relief
- Easy pick and place
- Plastic package has Underwriters Laboratory Flammability Classification 94V-O
- Complete device submersible temperature of 260 °C for 10 seconds in solder bath

Mechanical Data

Case: JEDEC DO-214AC molded plastic

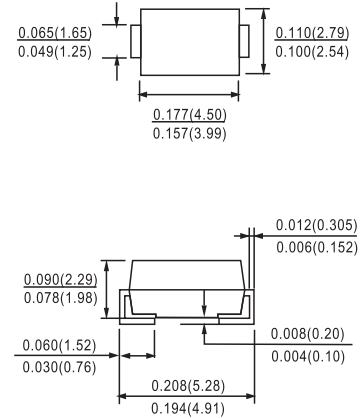
Terminals: Solder plated, solderable per MIL-STD-750,
Method 2026

Polarity: Indicated by cathode band

Standard packaging: 12mm tape (EIA-481)

Weight: 0.003 ounce, 0.093 gram

DO-214AC(SMA)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_L = 110^\circ\text{C}$	I_o	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60							A
Forward Voltage @ $I_F = 2.0\text{A}$	V_{FM}	1.10							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_{RM}	5.0 200							μA
Reverse Recovery Time (Note 1)	t_{rr}	2.5							μS
Typical Junction Capacitance (Note 2)	C_j	30							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$	16							K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150							$^\circ\text{C}$

- Note: 1. Measured with $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$,
2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
3. Mounted on P.C. Board with 8.0mm² land area.

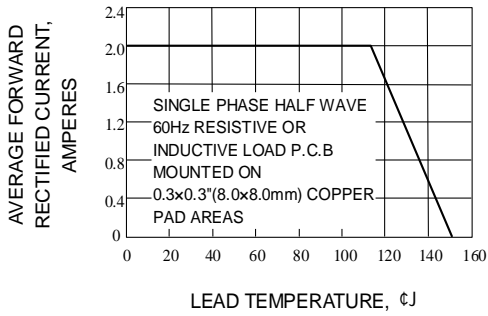


Fig. 1-FORWARD CURRENT DERATING CURVE

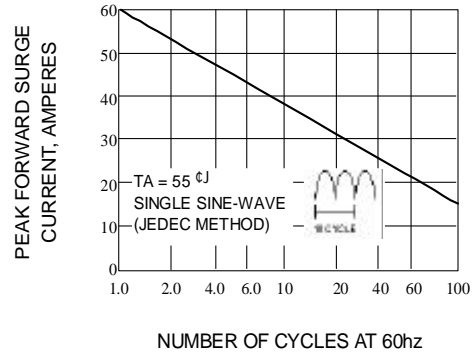


Fig. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

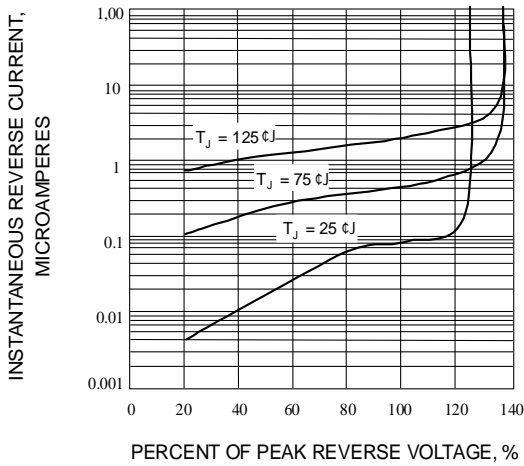


Fig. 3-TYPICAL REVERSE CHARACTERISTICS

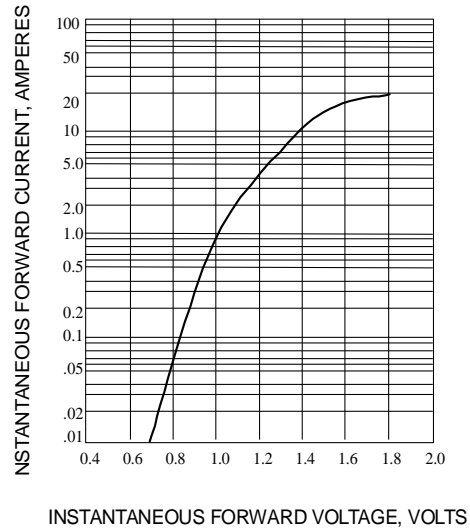


Fig. 4-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

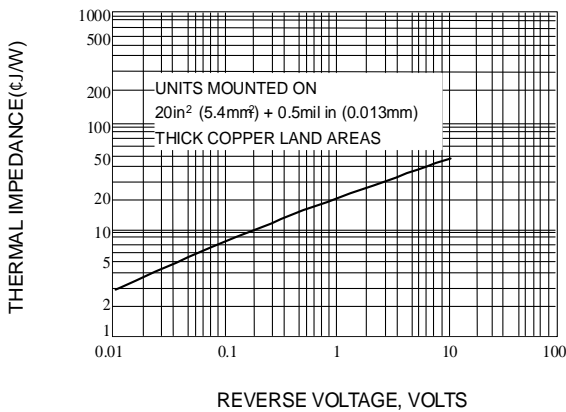


Fig. 5-TRANSIENT THERMAL IMPEDANCE

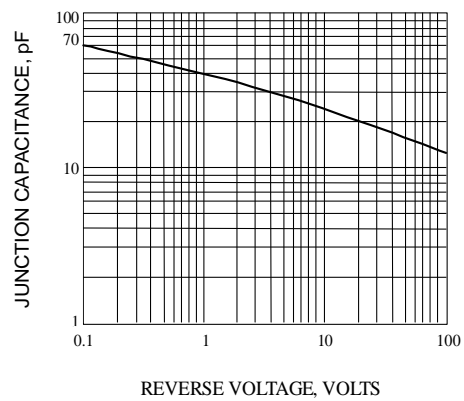


Fig. 6-TYPICAL JUNCTION CAPACITANCE